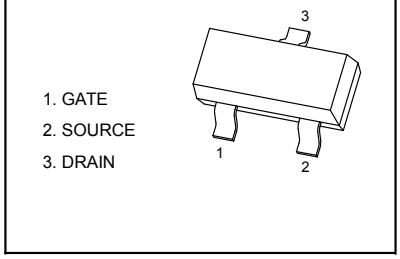
SI2310

SOT-23 Plastic-Encapsulate MOSFETS

30V N-Channel MOSFET

$V_{(BR)DSS}$	$R_{DS(on)}$Typ	I_D Max
60V	105mΩ@10V	3A
	125mΩ@4.5V	

SOT-23



DESCRIPTION

The SI2310 uses advanced trench technology to provide excellent $R_{DS(ON)}$, low gate charge and operation with gate voltage as low as 2.5V. This device is suitable for use as a battery protection or in other switching application.

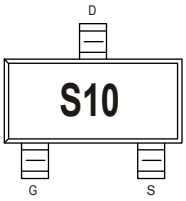
FEATURE

- High power and current handing capability
- Lead free product is acquired
- Surface mount package

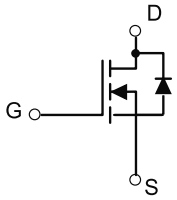
APPLICATION

- Battery Switch
- DC/DC Converter

MARKING



Equivalent circuit



PACKAGE SPECIFICATIONS

Package	Reel Size	Reel DIA. (mm)	Q'TY/Reel (pcs)	Box Size (mm)	QTY/Box (pcs)	Carton Size (mm)	Q'TY/Carton (pcs)
SOT-23	7'	178	3000	203×203×195	45000	438×438×220	180000

Maximum Ratings and Thermal Characteristics (TA = 25°C unless otherwise noted)

Parameter	Symbol	Limit	Unit
Drain-Source Voltage	V_{DS}	60	V
Gate-Source Voltage	V_{GS}	±20	
Continuous Drain Current	I_D	3	A
Pulsed Drain Current [1]	I_{DM}	10	A
Maximum Power Dissipation [1],[2]	P_D	0.35	W
Maximum Junction Temperature	T_J	150	°C
Storage Temperature	T_{stg}	-55 to 150	°C
Thermal Resistance from Junction-to-Ambient (t≤5s)	$R_{\theta JA}$	357	°C/W

Notes
1) Pulse width limited by maximum junction temperature.
2) Surface Mounted on FR4 Board, t ≤ 5 sec.

The above data are for reference only.

MOSFET ELECTRICAL CHARACTERISTICS

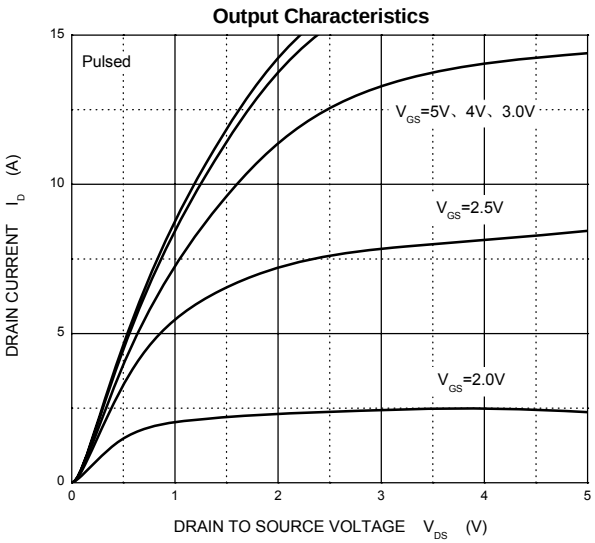
T_a=25℃ unless otherwise specified

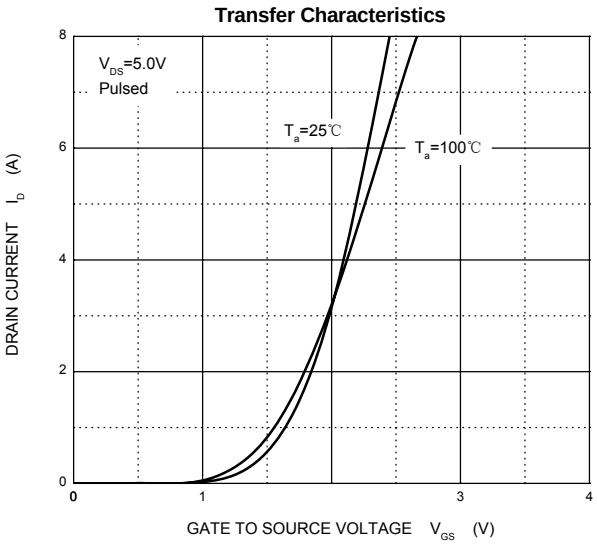
Parameter	Symbol	Test Condition	Min	Typ	Max	Unit
STATIC CHARACTERISTICS						
Drain-source breakdown voltage	$V_{(BR)DSS}$	V_{GS} = 0V, I_D =250μA	60			V
Zero gate voltage drain current	I_{DSS}	V_{DS} =60V,V_{GS} = 0V			1	μA
Gate-body leakage current	I_{GSS}	V_{GS} =±20V, V_{DS} = 0V			±100	nA
Gate threshold voltage (note 3)	$V_{GS(th)}$	V_{DS} =V_{GS}, I_D =250μA	0.5		2	V
Drain-source on-resistance (note 3)	$R_{DS(on)}$	V_{GS} =10V, I_D =3A			105	Ω
		V_{GS} =4.5V, I_D =3A			125	Ω
Forward tranconductance (note 3)	g_{FS}	V_{DS} =15V, I_D =2A	1.4			S
Diode forward voltage (note 3)	V_{SD}	I_S=3A, V_{GS} = 0V			1.2	V
DYNAMIC CHARACTERISTICS (note 4)						
Input Capacitance	C_{iss}	V_{DS} =30V,V_{GS} =0V,f =1MHz		247		pF
Output Capacitance	C_{oss}			34		pF
Reverse Transfer Capacitance	C_{rss}			19.5		pF
SWITCHING CHARACTERISTICS (note 4)						
Turn-on delay time	$t_{d(on)}$	V_{GS}=10V,V_{DD}=30V, I_D=1.5A,R_{GEN}=1Ω		6		ns
Turn-on rise time	t_r			15		ns
Turn-off delay time	$t_{d(off)}$			15		ns
Turn-off fall time	t_f			10		ns
Total Gate Charge	Q_g	V_{DS} =30V,V_{GS} =4.5V,I_D =3A		6		nC
Gate-Source Charge	Q_{gs}			1		nC
Gate-Drain Charge	Q_{gd}			1.3		nC

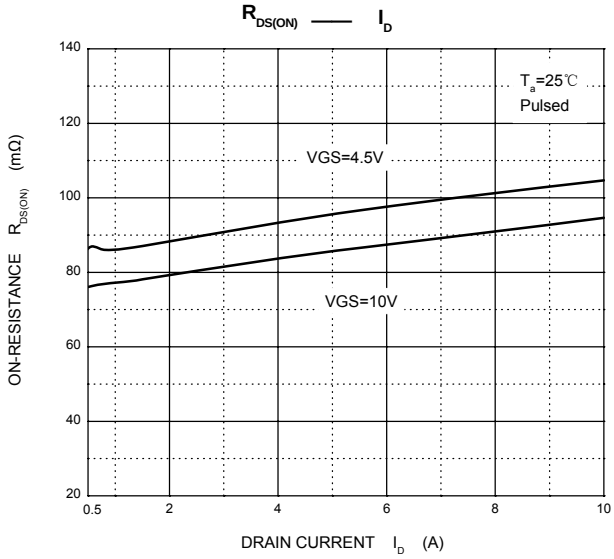
Notes :

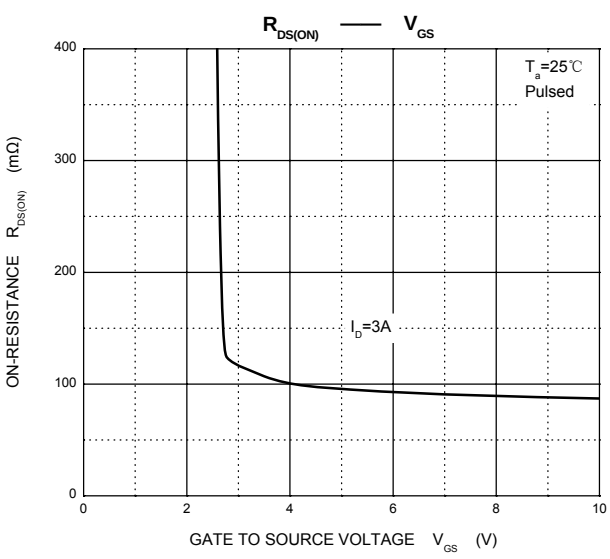
1. Repetitive rating : Pulse width limited by junction temperature.
2. Surface mounted on FR4 board , t≤10s.
3. Pulse Test : Pulse Width≤300μs, Duty Cycle≤0.5%.
4. Guaranteed by design, not subject to producting.

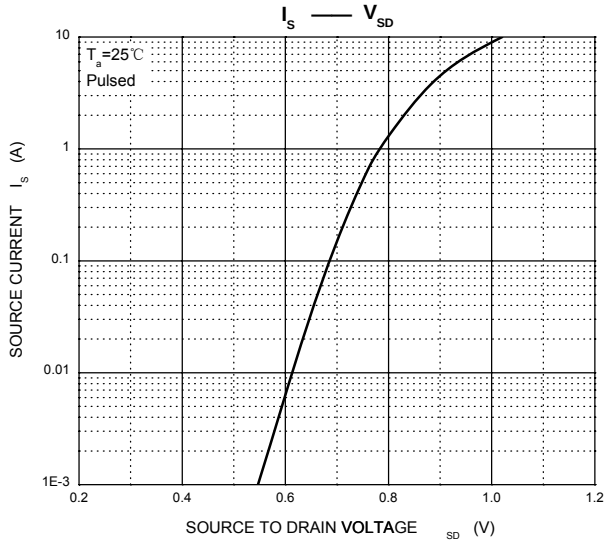
Typical Characteristics

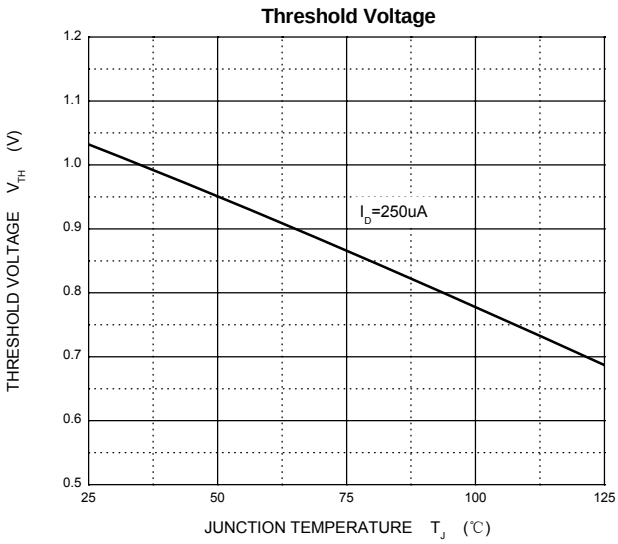






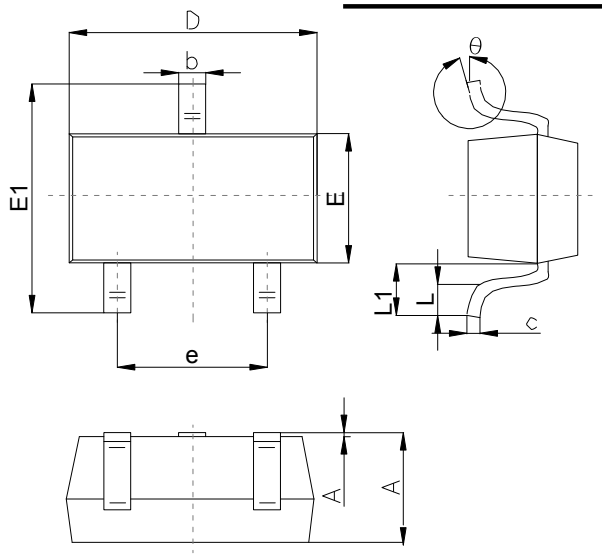






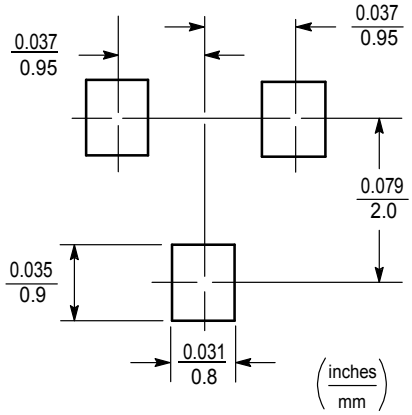
Outlitne Drawing

SOT-23 Package Outline Dimensions



Symbol	Dimensions In Millimeters		
	Min	Typ	Max
A	1.00		1.40
A1			0.10
b	0.35		0.50
c	0.10		0.20
D	2.70	2.90	3.10
E	1.40		1.60
E1	2.4		2.80
e		1.90	
L	0.10		0.30
L1	0.4		
θ	0°		10°

Suggested Pad Layout



Note:
1. Controlling dimension:in/millimeters. 2.General tolerance: ±0.05mm.
3.The pad layout is for reference purposes only.